

New Products

**Low-springback,
Low-warpage FPC using
Flame-resistant Solder
resist**

Recently, as electric devices including smartphones and tablets have been becoming increasingly smaller and thinner, ease of mounting into a housing becomes required of FPCs. To meet the market demand, Fujikura has developed an FPC characterized by low springback and low warpage using a new photosensitive solder resist.

The solder resist FPC facilitates mounting of the FPC into a housing because of its flexibility superior to that of polyimide-based coverlay film and capability of bending and holding the shape. The solder resist also offers highly accurate positioning of the opening by a photolithography method and good adhesion to anisotropic conductive film (ACF). In addition, the solder resist FPC is flame retardant without containing bromine-based flame-retardant and is UL 94-certified.

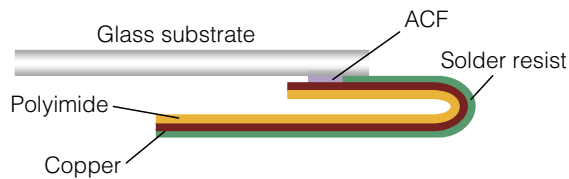


Fig. 1. Product image.

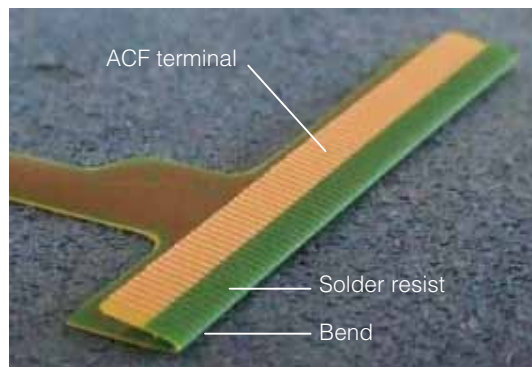


Fig. 2. Applications of the product.

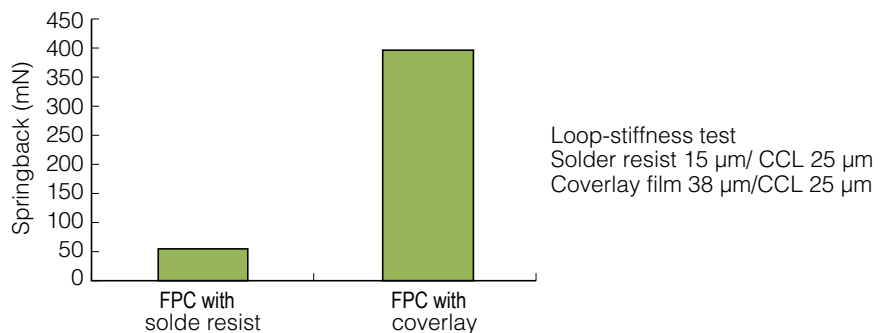


Fig. 3. Comparison of springback.

[Information]
Electronics Business Company
Printed Circuit Division
Tel : +81 43 484 3950 Fax : +81 43 484 3985
E-mail : askfpc@jp.fujikura.com